IOxOS Technologies unveils its new Multi Purpose Carrier platform based on latest Xilinx Virtex-6T FPGA for high-density IO demanding applications

Geneva (Switzerland), November 2010 - **IOxOS Technologies** introduces the **MPC_1200**, a 6U VME64x **Multi Purpose IO Carrier** board based on latest **Xilinx Virtex-6T** and **Spartan-6** 40nm FPGAs. Thanks to the high capacity and the extreme performance of these high-end FPGA devices, very sophisticated applications can be implemented in a standard VME64x environment.

Compared to other products based on mezzanine cards extension (i.e, FMC or XMC), the MPC_1200 edge-to-edge interconnection solution provides full PCB area utilization, direct VME64x front panel access without any restriction on front panel connectors type, and enhanced air cooling capability with standard heat-sink, while keeping modularity and versatility.

For applications requiring a high-density IO connection, a single MPC_1200 carrier can control several VME64x units drastically reducing the cost per IO point of connection. The interconnect expansion is made with high-performance connectors supporting data rates up to **11 Gb/s**, making possible to interface today's high-speed protocols such as Gigabit Ethernet and PCI Express. The MPC_1200 also features the new 3M Ultra Hard Metric (UHM) connector technology which enhances the legacy **VME64x P0** connector with high-speed serial protocols supporting data rates up to 5 Gb/s (such as PCI Express and Serial RapidIO).

The MPC_1200 carrier board can host two single-width or one dual-width MPF (Multi Purpose Front-end) IO modules for expansion purposes. A dual-width MPF IO module provides extended PCB area (around 50% of an entire VME 6U board) with full front panel accessibility. IOxOS Technologies is developing a comprehensive family of MPF IO modules to make the most of the MPC_1200 capabilities. The first member of this product line features a Freescale P2020 dual-core processor and two FMC (LPC) extension slots, to convert the MPC_1200 in a versatile Single Board Computer with embedded FPGA capability to target high-density IO applications.

TOSCA II, a comprehensive FPGA Design Kit developed by IOxOS Technologies, is available for the implementation and integration of custom applications within the MPC_1200 on-board **Virtex-6T FPGA**, which supports the following FF1156 devices: LX130T, LX195T, LX240T, LX365T, SX315T and SX475T.

The MPC_1200 has been developed in collaboration with the Institute Laue-Langevin (ILL) in Grenoble (France), an international research centre at the leading edge of neutron science and technology.

IOxOS Technologies SA, based in the Geneva area (Switzerland), is an electronic design company offering innovative solutions to system integrators in the aerospace, physics and telecommunication industries. It combines a comprehensive product line with engineering, consulting and training services covering both hardware and software

Institute Laue-Langevin (ILL), based in Grenoble (France), is an international research centre at the leading edge of neutron science and technology. The Institute operates one of the most intense neutron sources in the world, feeding intense beams of neutrons to a suite of 40 high-performance instruments that are constantly upgraded